

# SOT740-2

plastic low profile ball grid array package; 256 balls; body 17 x 17 x 1 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LBGA256
<b>Package type industry code</b>	LBGA256
<b>Package style descriptive code</b>	LBGA (low profile ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-192
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	4-8-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	16.8	-	17	17.2	mm
E	package width	16.8	-	17	17.2	mm
A	seated height	[tbd]	-	1.55	1.55	mm
A <sub>2</sub>	package height	0.9	-	1	1.1	mm
n <sub>2</sub>	actual quantity of termination	-	-	256	-	



## 2. Package outline

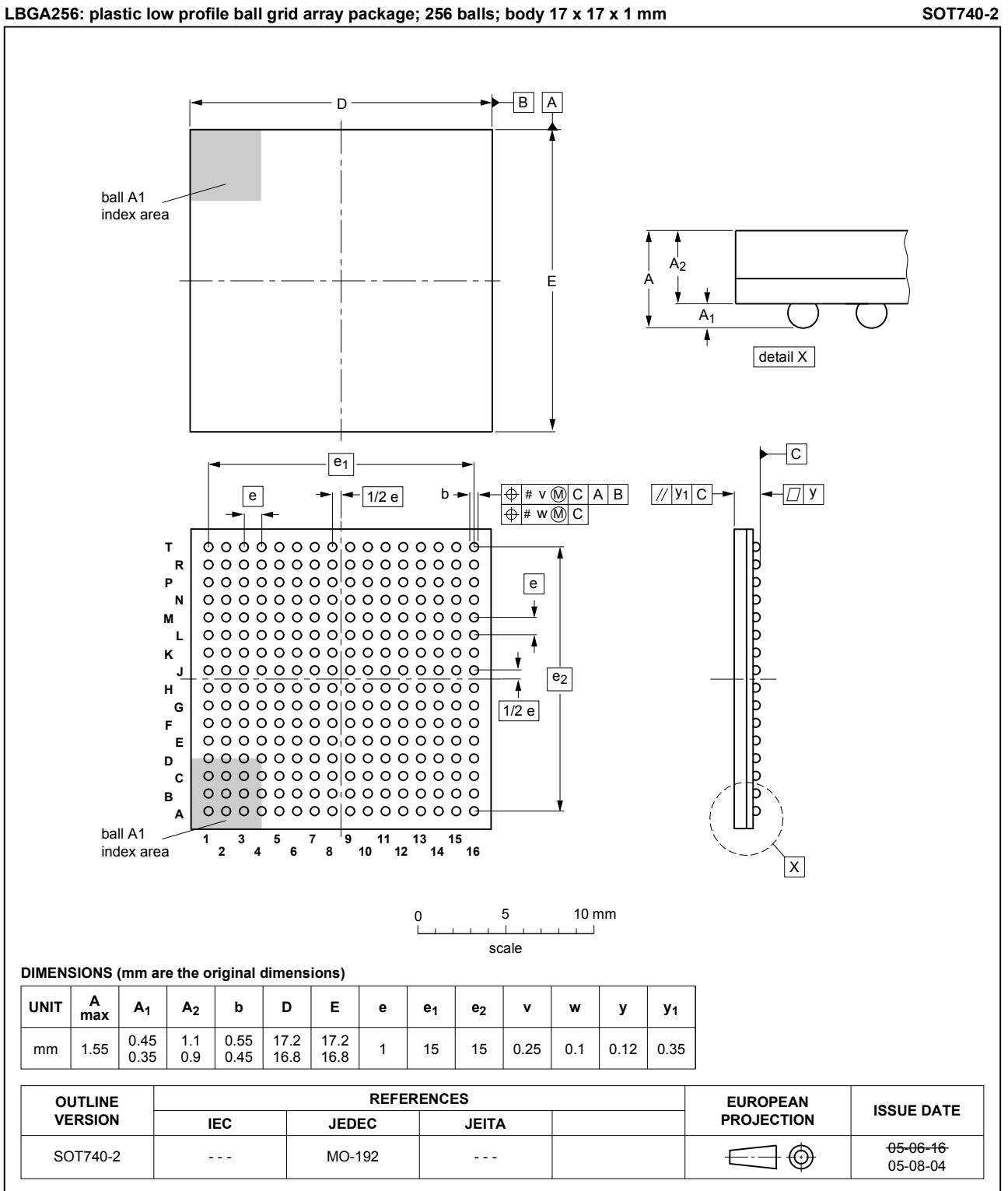


Fig. 1. Package outline LPGA256 (SOT740-2)

### 3. Soldering

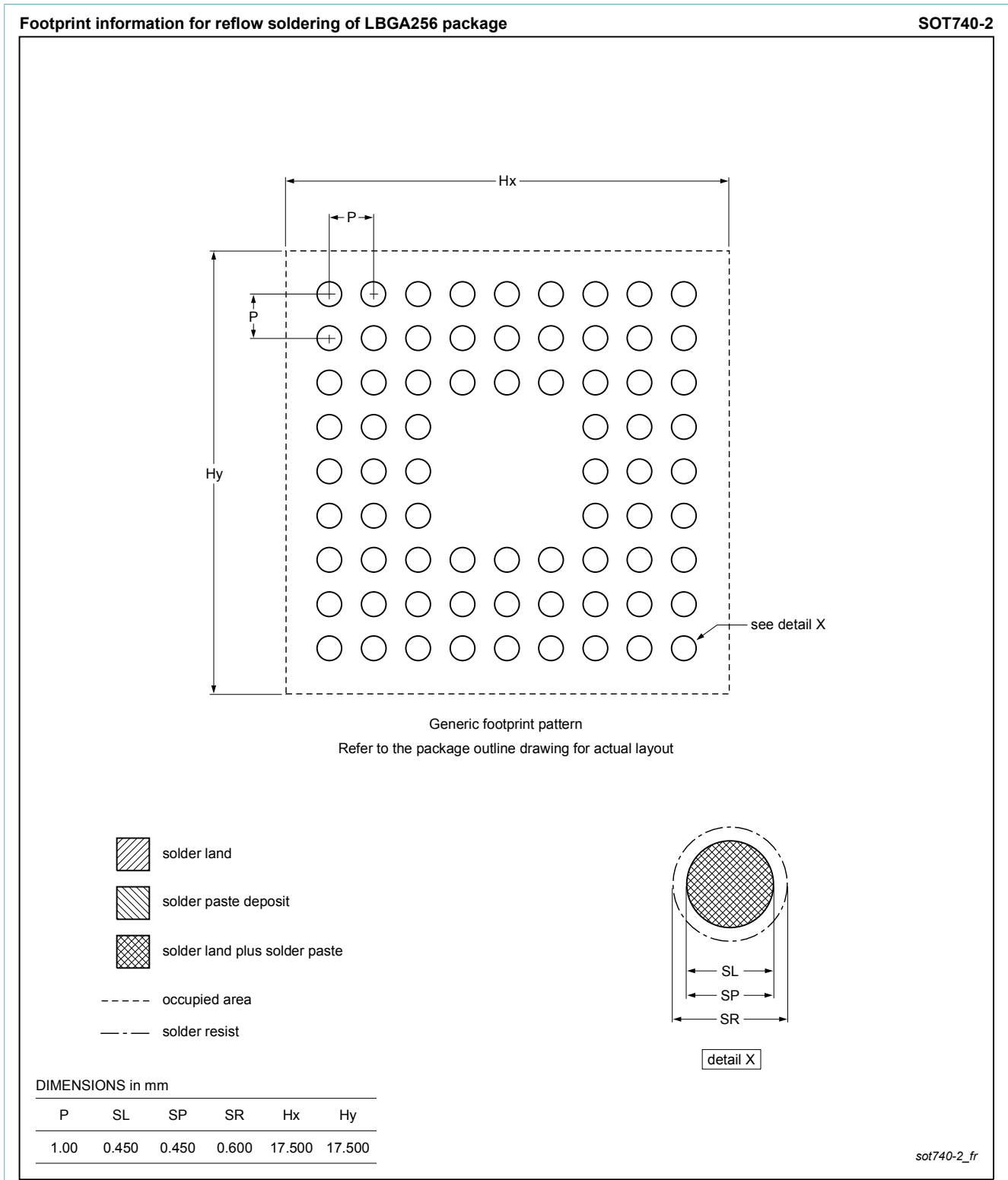


Fig. 2. Reflow soldering footprint for LBG256 (SOT740-2)

## 4. Legal information

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Date of release: 8 February 2016

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